GOODWORK

50P03DF

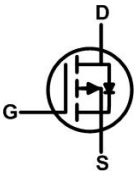
P-Ch 30V Fast Switching MOSFETs

Description

The 50P03DF is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

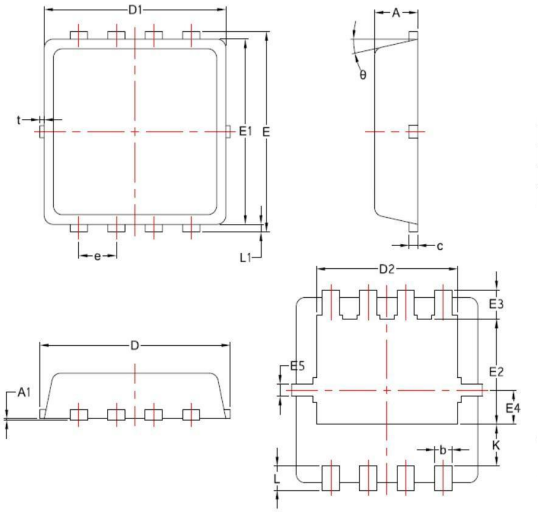
The 50P03DF meet the RoHS and Gree Product requirement 100% EAS guaranteed with full function reliability approved.

100% EAS Guaranteed
Green Device Available
Super Low Gate Charge
Excellent CdV/dt effect decline
Advanced high cell density Trench technology



Product Summary

BVDSS	RDSON	ID
-30V	8.5mΩ	-50A



PDFN3X3

Dimensions In Millimeters					
Symbol	MIN.	MAX.	Symbol	MIN.	MAX.
A	0.7	0.85	E3	0.28	0.68
A1	/	0.05	E4	0.37	0.77
b	0.20	0.40	E5	0.10	0.30
c	0.10	0.25	e	0.60	0.70
D	3.15	3.45	K	0.59	0.89
D1	3.00	3.25	L	0.30	0.50
D2	2.40	2.65	L1	0.06	0.20
E	3.00	3.20	T	0	0.13
E1	2.90	3.20	Θ	/	12°
E2	1.54	1.94			

Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V_{DS}	Drain-Source Voltage	-30		V
V_{GS}	Gate-Source Voltage	±25		V
I_D@T_C=25°C	Continuous Drain Current, V_{GS} @ -10V[1]	-50		A
I_D@T_C=100°C	Continuous Drain Current, V_{GS} @ -10V[1]	-32		A
I_{DM}	Pulsed Drain Current[2]	-150		A
EAS	Single Pulse Avalanche Energy[3]	125		mJ
I_{AS}	Avalanche Current	-50		A
P_D@T_A=25°C	Total Power Dissipation[4]	5	2.0	W
T_{STG}	Storage Temperature Range	-55 to 150		°C
T_J	Operating Junction Temperature Range	-55 to 150		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	62	°C/W

50P03DF

Electrical Characteristics (T_J=25℃ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D= -250μA	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}= -30V, V_{GS}=0V,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS}=0V, V_{GS}= ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D= -250μA	-1.0	-1.6	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance Note3	V_{GS}= -10V, I_D= -10A	-	8.5	14	mΩ
		V_{GS}= -4.5V, I_D= -5A	-	17	24	
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}= -15V, V_{GS}=0V, f=1.0MHz	-	1770	-	pF
C_{oss}	Output Capacitance		-	233	-	pF
C_{rss}	Reverse Transfer Capacitance		-	206	-	pF
Q_g	Total Gate Charge	V_{DS}= -15V, I_D= -5A, V_{GS}= -10V	-	22	-	nC
Q_{gs}	Gate-Source Charge		-	1.0	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	1.8	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DD}= -15V, I_D= -10A, V_{GS}=-10V, R_{GEN}=2.5Ω	-	9	-	ns
t_r	Turn-on Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	48	-	ns
t_f	Turn-off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-15	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-60	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_S= -15A	-	-0.8	-1.2	V
trr	Reverse Recovery Time	T_J=25℃, V_{DD}= -24V,I_F=-2.8A, dI/dt=-100A/μs	-	64	-	ns
Qrr	Reverse Recovery Charge		-	25	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25℃, V_{GS}=10V, R_G=25Ω, L=0.5mH, I_{AS}=-12.7A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

RATING AND CHARACTERISTIC CURVES (50P03DF)

Figure1: Output Characteristics

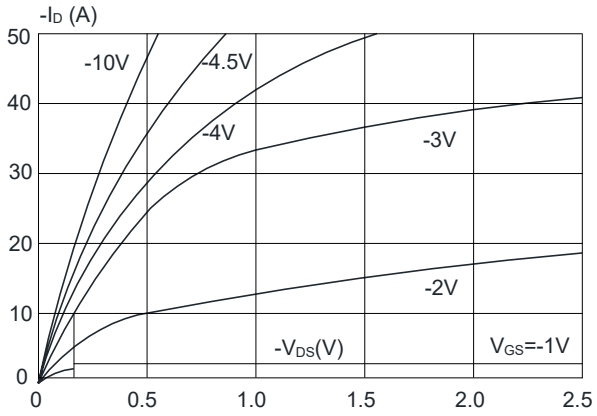


Figure 2: Typical Transfer Characteristics

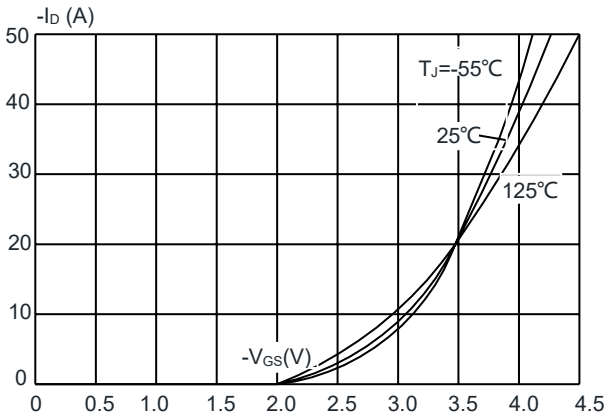


Figure 3: On-resistance vs. Drain Current

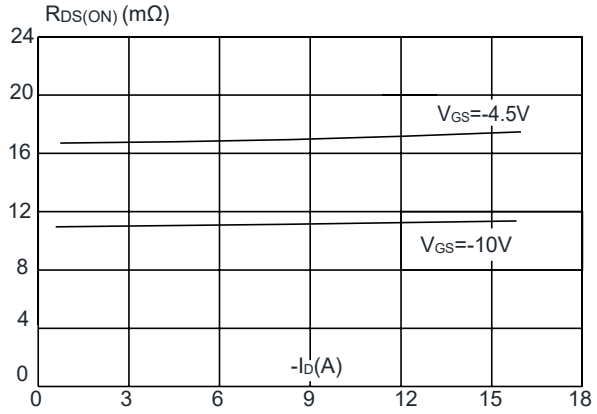


Figure 4: Body Diode Characteristics

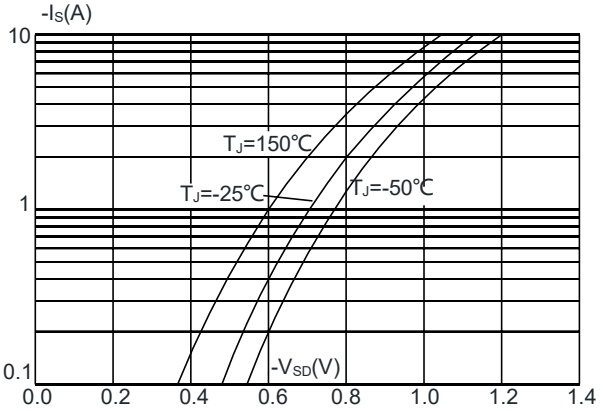


Figure 5: Gate Charge Characteristics

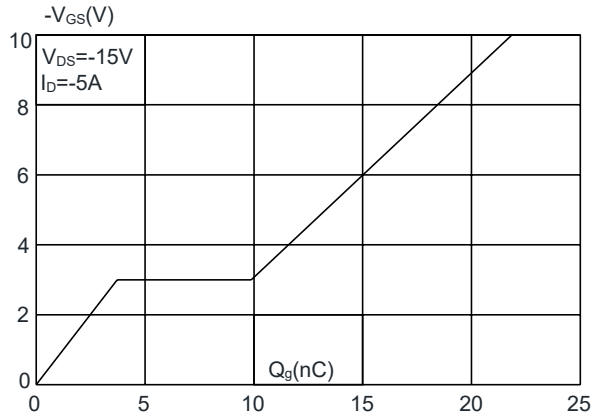
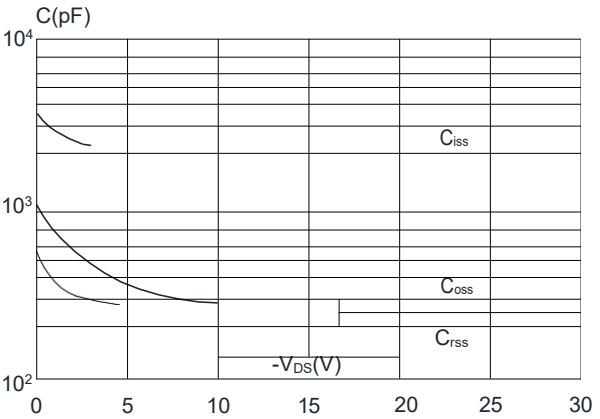


Figure 6: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES (50P03DF)

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

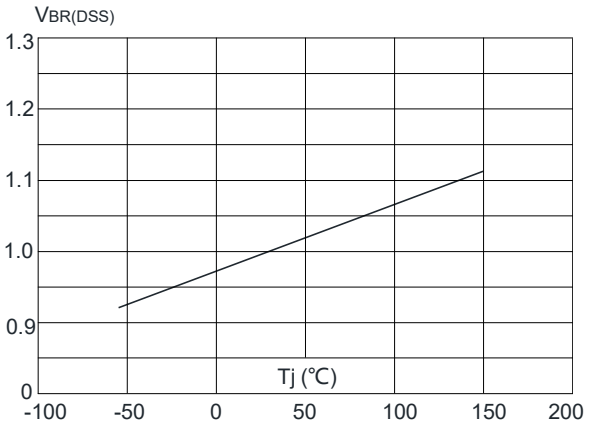


Figure 8: Normalized on Resistance vs. Junction Temperature

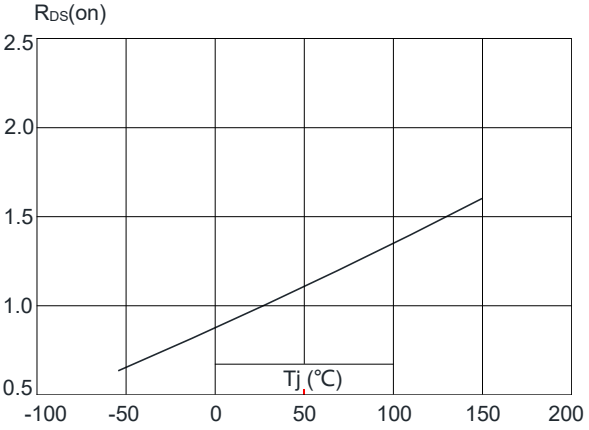


Figure 9: Maximum Safe Operating Area

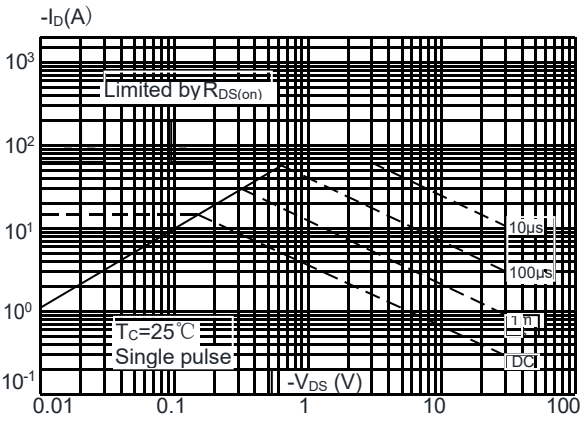


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

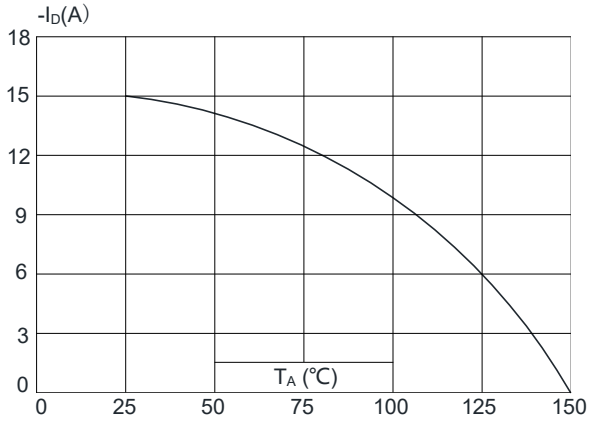
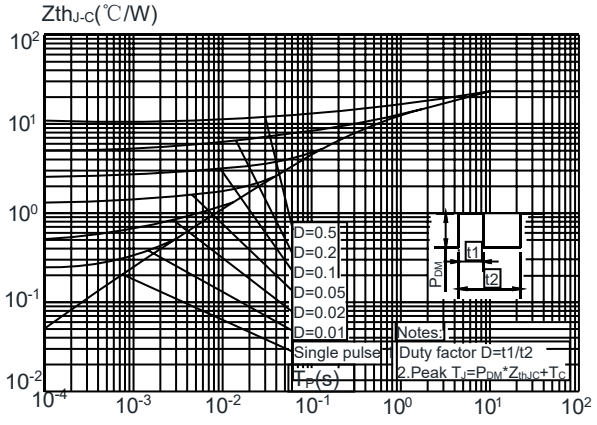
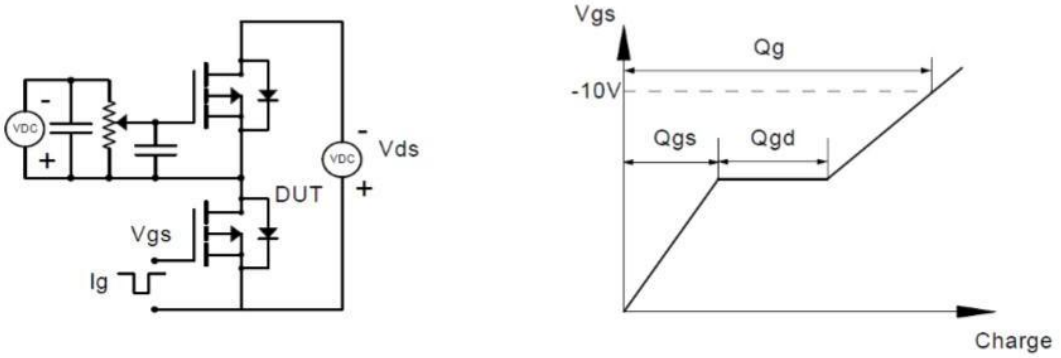


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

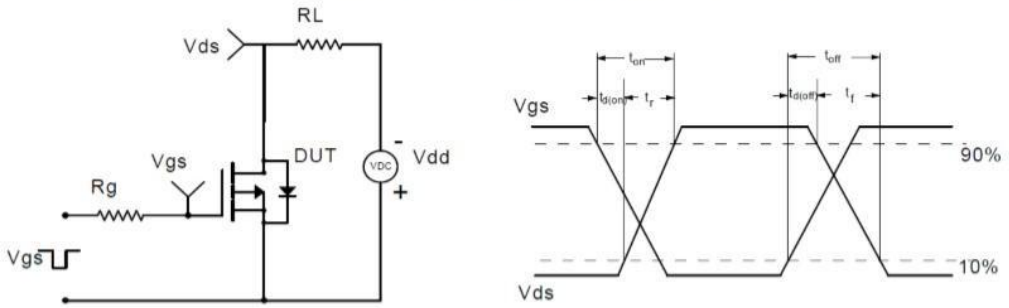


Test Circuit

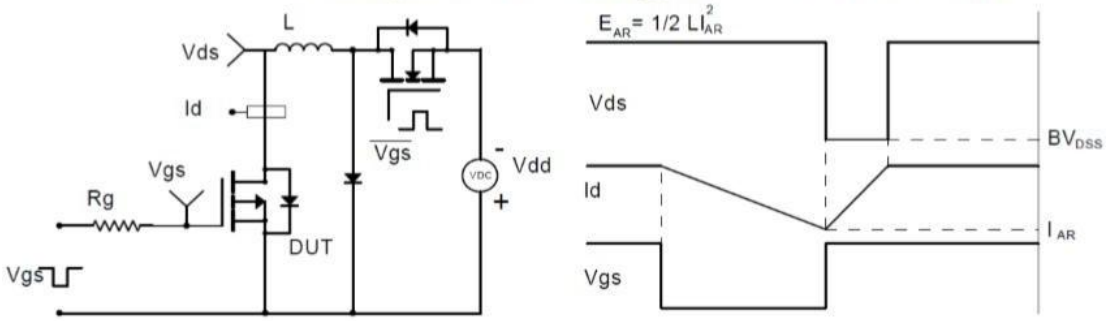
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms